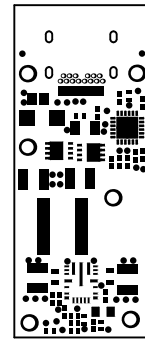
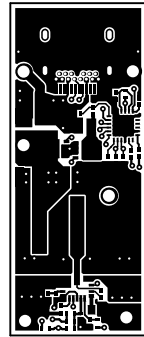


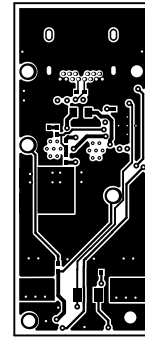
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20807	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 5/25/2017 5:36:19 PM	TEXAS INSTRUMENTS	



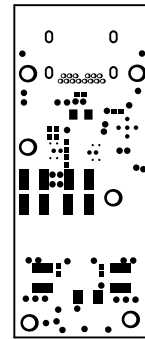
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20807	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 5/25/2017 5:36:22 PM	TEXAS INSTRUMENTS	



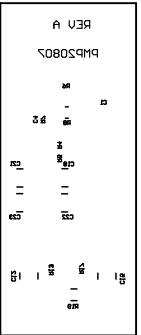
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20807	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Layer1			
PLOT NAME = Top Layer	GENERATED : 5/25/2017 5:36:25 PM	TEXAS INSTRUMENTS	



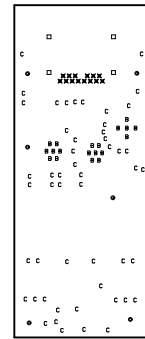
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20807	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer4			
PLOT NAME = Bottom Layer	GENERATED : 5/25/2017 5:36:28 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20807	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 5/25/2017 5:36:31 PM	TEXAS INSTRUMENTS	



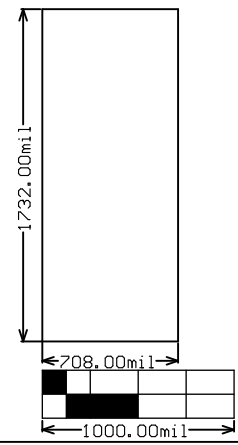
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20807	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 5/25/2017 5:36:34 PM	TEXAS INSTRUMENTS	



Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance	Hole Length
B	19	7.87mil (0.200mm)	PTH	Round	Top Layer1 - Bottom Layer4		-
C	51	12.00mil (0.305mm)	PTH	Round	Top Layer1 - Bottom Layer4		-
X	14	15.75mil (0.400mm)	PTH	Round	Top Layer1 - Bottom Layer4		-
●	6	63.00mil (1.600mm)	PTH	Round	Top Layer1 - Bottom Layer4		-
□	4	23.62mil (0.600mm)	PTH	Slot	Top Layer1 - Bottom Layer4		47.24mil (1.200mm)
	<b>94 Total</b>						

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.  
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20807	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 5/25/2017 5:36:37 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20807	REV: A	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 5/25/2017 5:36:40 PM	TEXAS INSTRUMENTS	



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